

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.17457	90.0	3.735
	Lead alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00097	0.5	0.02075
	Lead alloy	Silver (Ag)	7440-22-4	0.00485	2.5	0.10375
	Lead alloy	Antimony (Sb)	7440-36-0	0.01358	7.0	0.2905
	Subtotal			0.19397	100	4.15
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.30848	100.0	6.6
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.01683	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.05609	0.1	1.2
	Copper alloy	Copper (Cu)	7440-50-8	56.01413	99.87	1,198.44
	Subtotal			56.08705	100	NaN
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26196	100.0	27
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00561	0.03	0.12
	Copper alloy	Iron (Fe)	7439-89-6	0.0187	0.1	0.4
	Copper alloy	Copper (Cu)	7440-50-8	18.67138	99.87	399.48
	Subtotal			18.69569	100	400
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.05842	5.0	1.25
	Lead alloy	Silver (Ag)	7440-22-4	0.02921	2.5	0.625
	Lead alloy	Lead (Pb)	7439-92-1	1.08084	92.5	23.125
Subtotal			1.16847	100	25	
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0.00421	0.1	0.09
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.85318	91.6	82.44
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.03786	0.9	0.81
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29446	7.0	6.3
	Copper alloy	Manganese (Mn)	7439-96-5	0.01683	0.4	0.36
	Subtotal			4.20654	100	90
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.26641	1.5	5.7
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	1.68729	9.5	36.1
	Filler	Silica fused	60676-86-0	15.62959	88.0	334.4
	Carbon Black	Carbon black	1333-86-4	0.17761	1.0	3.8
Subtotal			17.7609	100	380	
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01784	100.0	0.3817
	Pure metal	Aluminium (Al)	7429-90-5	0.29913	100.0	6.4
	Subtotal			0.31697	200	6.7817
Total			100.00003	100	NaN	

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